

INNOVATION

ACTIV HEAT

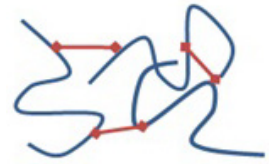
FLEXIBLE & DRY ADHESIVE FOR PERMANENT BONDING



PRODUCT

DISCOVER OUR LATEST PU ADHESIVE TECHNOLOGY ENSURING A PERMANENT ADHESION.

A unique polyurethane (PU) adhesive enriched with curing agents, acting as bonding, whose thermoset properties are activated by a combination of heat & pressure during a time depending of the substrate nature.



Reinforcing curing agent allows thermoset properties

KEY PROPERTIES



Structural bonding



Flexible



Good chemical resistance



More than 90% transparency

CUSTOMER BENEFITS



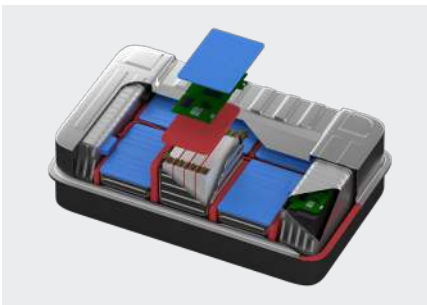
Faster to implement than other thermoset solutions



Storage & Drying at room temperature

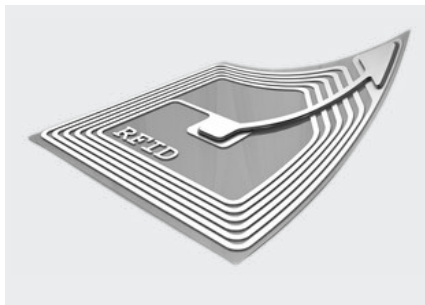
APPLICATIONS EXAMPLES

This product is recommended when a structural, transparent and flexible bond is required.



POWER MANAGEMENT

- ▶ Fuel cell: Adhesion to Nafion
- ▶ Bus bars



RFID

- ▶ Inlay
- ▶ Coverlay



SAFETY

- ▶ Coverlay
- ▶ Banknotes
- ▶ Inlay

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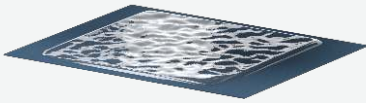
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CONVERTING PROCESSES

COATING



Double side adhesive film + protective liner (Need a prebonding around 70°C)



Adhesive coated on a custom flexible substrate

CURING



A mix of temperature, pressure and time activate the thermoset, which is the chemical permanent bonding.

COMPATIBLE CURING PROCESS

- ▶ Roll to Roll lamination
- ▶ Press lamination

The curing process is chosen according to the thickness of the substrate.

TESTED SUBSTRATES FOR LAMINATION



▶ PET



▶ PC



▶ Metals



▶ Papers

INDICATIVE VALUES

Adhesion values (N/cm)	Substrate	Activation conditions
16	Copper	180°C - 8bars - 60 sec
6	Aluminum	140°C - 10 bars - 5min
Substrate broken	PET	140°C - 10 bars - 5min
Substrate broken	Paper	1m/min - 130°C
Substrate broken	PC	140°C - 10bars - 5min

T-peel test according to ASTM D882 standard